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September 2006

FGD3N60LSD IGBT

Features

- · High Current Capability
- Very Low Saturation Voltage: V_{CE(sat)} = 1.2 V @ I_C = 3A
- · High Input Impedance

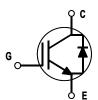
Applications

- · HID Lamp Applications
- · Piezo Fuel Injection Applications

Description

Fairchild's Insulated Gate Bipolar Transistors (IGBTs) provide very low conduction losses. The device is designed for applications where very low On-Voltage Drop is a required feature.





Absolute Maximum Ratings

Symbol	Description		FGD3N60LSD	Units
V _{CES}	Collector-Emitter Voltage		600	V
V _{GES}	Gate-Emitter Voltage		± 25	V
I _C	Collector Current	@ T _C = 25°C	6	Α
	Collector Current	@ T _C = 100°C	3	Α
I _{CM (1)}	Pulsed Collector Current	(1)	25	Α
lF	Diode Continous Forward Current	@ T _C = 100°C	3	Α
I FM	Diode Maximum Forward Current		25	Α
P_{D}	Maximum Power Dissipation	@ T _C = 25°C	40	W
	Derating Factor		0.32	W/°C
TJ	Operating Junction Temperature		-55 to +150	°C
T _{stg}	Storage Temperature Range		-55 to +150	°C
T _L	Maximum Lead Temp. for Soldering Purposes, 1/8" from Case for 5 Seconds	3	250	°C

Notes :

(1) Repetitive rating : Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Units	
R _θ JC (IGBT)	Thermal Resistance, Junction-to-Case		3.1	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (PCB Mount) (2)		100	°C/W	

Notes

(2) Mounted on 1" squre PCB (FR4 or G-10 Material)

Package Marking and Ordering Information

Device Marking Device		Package	Reel Size	Tape Width	Quantity	
FGD3N60LSD	FGD3N60LSDTM	D-PAK	380mm	16mm	2500	

Electrical Characteristics of the IGBT $T_C = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Charact	eristics					
BV _{CES}	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 250uA$	600			V
ΔB _{VCES} / ΔΤ _J	Temperature Coefficient of Breakdown Voltage	V_{GE} = 0V, I_C = 1mA		0.6		V/°C
I _{CES}	Collector Cut-Off Current	V _{CE} = V _{CES} , V _{GE} = 0V			250	uA
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$			± 100	nA
On Charact	eristics					
V _{GE(th)}	G-E Threshold Voltage	I_C = 3mA, V_{CE} = V_{GE}	2.5	3.2	5.0	V
V _{CE(sat)}	Collector to Emitter	I _C = 3A, V _{GE} = 10V		1.2	1.5	V
02(001)	Saturation Voltage	I _C = 6A, V _{GE} = 10V		1.8		V
Dynamic Cl	naracteristics	<u> </u>			I	
C _{ies}	Input Capacitance	V _{CE} = 25V, V _{GE} = 0V,		185		pF
C _{oes}	Output Capacitance	f = 1MHz		20		pF
C _{res}	Reverse Transfer Capacitance			5.5		pF
	Characteristics	V 480 V I 30		40		ne
$t_{d(on)}$	Turn-On Delay Time	$V_{CC} = 480 \text{ V}, I_{C} = 3A,$		40		ns
t _r	Rise Time	$R_G = 470\Omega$, $V_{GE} = 10V$, Inductive Load, $T_C = 25^{\circ}C$		40		ns
$t_{d(off)}$	Turn-Off Delay Time			600		ns
t _f	Fall Time			600		ns
E _{on}	Turn-On Switching Loss			250		uJ
E _{off}	Turn-Off Switching Loss			1.00		mJ
E _{ts}	Total Switching Loss			1.25		mJ
t _{d(on)}	Turn-On Delay Time	V _{CC} = 480 V, I _C = 3A,		40		ns
t _r	Rise Time	R_G = 470 Ω , V_{GE} = 10V, Inductive Load, T_C = 125°C		45		ns
t _{d(off)}	Turn-Off Delay Time	Inductive Load, 1 _C = 123 C		620		ns
t _f	Fall Time			800		ns
E _{on}	Turn-On Switching Loss			300		uJ
E _{off}	Turn-Off Switching Loss			1.9		mJ
E _{ts}	Total Switching Loss			2.2		mJ
Q _g	Total Gate Charge	V _{CE} = 480 V, I _C = 3A,		12.5		nC
Q _{ge}	Gate-Emitter Charge	V _{GE} = 10V		2.8		nC
Q _{gc}	Gate-Collector Charge			4.9		nC
L _e	Internal Emitter Inductance	Measured 5mm from PKG		7.5		nH

Electrical Characteristics of DIODE $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Units
V_{FM}	Diode Forward Voltage	I _F = 3A	T _C = 25°C		1.5	1.9	V
			T _C = 100°C		1.55		
t _{rr}	Diode Reverse Recovery Time	I _F = 3A,	T _C = 25°C		234		ns
		di/dt = 100A/us VR = 200V	T _C = 100°C				
I _{rr}	Diode Peak Reverse Recovery Current	VR = 200 V	T _C = 25°C		2.64		Α
			T _C = 100°C				
Q _{rr}	Diode Reverse Recovery Charge		T _C = 25°C		309		nC
			T _C = 100°C				

Typical Performance Characteristics

Figure 1. Typical Output Characteristics

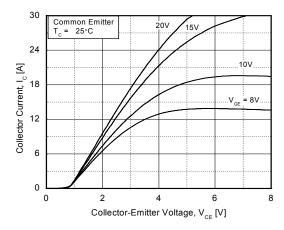


Figure 3. Typical Output Characteristics

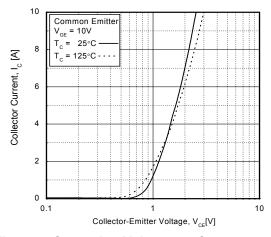


Figure 5. Saturation Voltage vs. Case

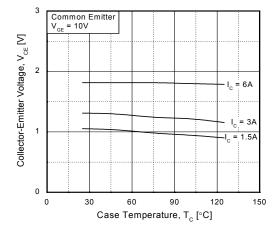


Figure 2. Typical Output Characteristics

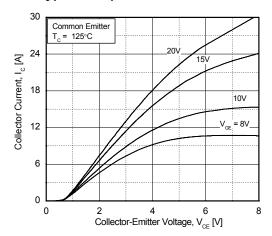


Figure 4. Transfer Characteristics

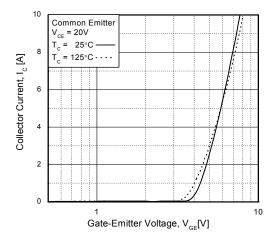
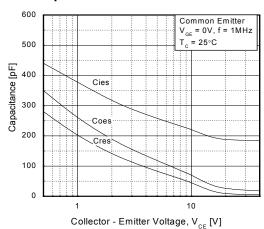


Figure 6. Capacitance Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Gate Charge

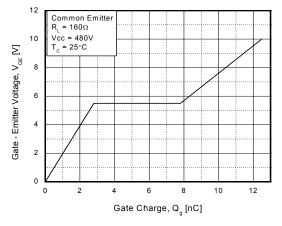


Figure 9. Turn-Off Characteristics vs. Gate Resistance

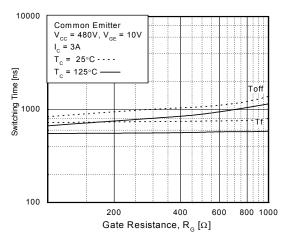


Figure 11. Turn-On Characteristics vs. Collector Current

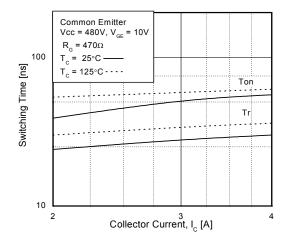


Figure 8. Turn-On Characteristics vs. Gate Resistance

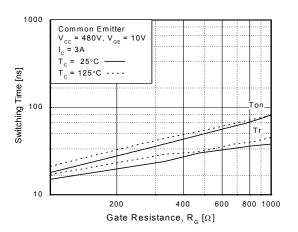


Figure 10. Switching Loss vs. Gate Resistance

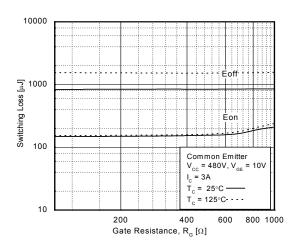
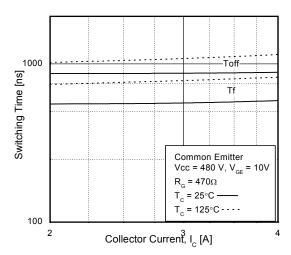


Figure 12. Turn-Off Characteristics vs. Collector Current



Typical Performance Characteristics (Continued)

Figure 13. Switching Loss vs. Collector Current

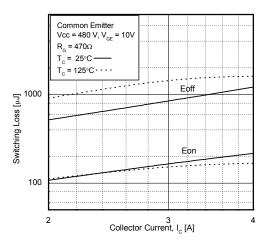


Figure 14. Forward Characteristics

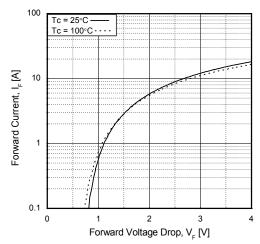


Figure 15. Forward Voltage Drop Vs Tj

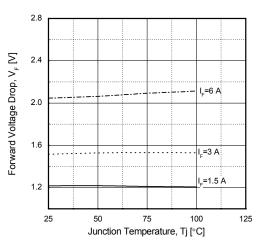


Figure 16. SOA Characteristics

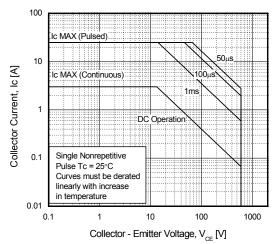
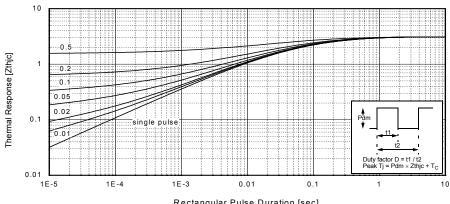


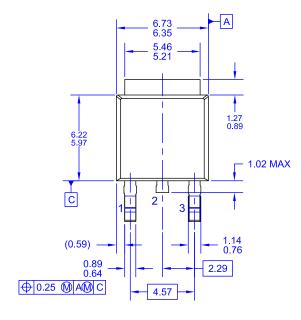
Figure 17. Transient Thermal Impedance of IGBT

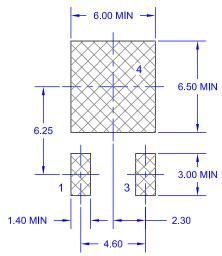


Rectangular Pulse Duration [sec]

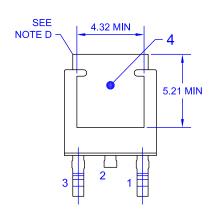
Mechanical Dimensions

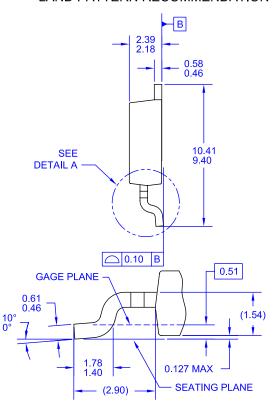
D-PAK





LAND PATTERN RECOMMENDATION





NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC, TO-252, ISSUE C, VARIATION AA.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
 C) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- D) HEAT SINK TOP EDGE COULD BE IN CHAMFERED CORNERS OR EDGE PROTRUSION.
- E) PRESENCE OF TRIMMED CENTER LEAD
- IS OPTIONAL.
 F) DIMENSIONS ARE EXCLUSSIVE OF BURSS,
- MOLD FLASH AND TIE BAR EXTRUSIONS.
- G) LAND PATTERN RECOMENDATION IS BASED ON IPC7351A STD
- TO220P1003X238-3N.
 H) DRAWING NUMBER AND REVISION: MKT-TO252A03REV8

Dimensions in Millimeters

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